

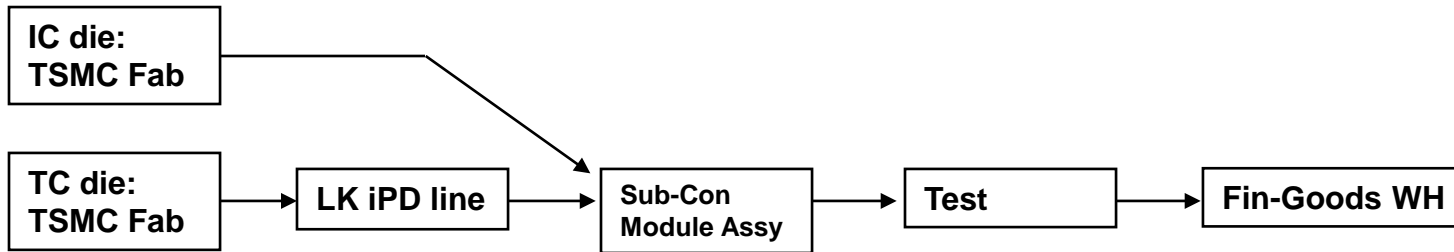
QUALIFICATION PLAN #10524			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
High Temperature Operating Life (HTOL)*	JEDEC <i>JESD22-A108</i>	<b>1*77</b>	<b>Passed</b>
		<b>1*77</b>	<b>Passed</b>
Early Life Failure (ELF)	MIL-STD-883, <i>Method 1015</i>	<b>3*667</b>	<b>Passed</b>
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	<b>1*45</b>	<b>Passed</b>
		<b>1*45</b>	<b>Passed</b>
Latch-Up	JEDEC <i>JESD78</i>	<b>6</b>	<b>Passed</b>
		<b>6</b>	<b>Passed</b>
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JDS-001-2011</i>	<b>3/voltage</b>	<b>Passed</b>
		<b>3/voltage</b>	<b>Passed</b>
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	<b>3/voltage</b>	<b>Passed</b>
		<b>3/voltage</b>	<b>Passed</b>
Electrostatic Discharge <i>Machine Model</i>	JEDEC <i>JESD22-A115</i>	<b>3/voltage</b>	<b>Passed</b>
		<b>3/voltage</b>	<b>Passed</b>
Electrostatic Discharge <i>15kV IEC HBM</i>	IEC <i>6100-4-2</i>	<b>3/voltage</b>	<b>Passed</b>

\*Preconditioned per JEDEC/IPC J-STD-020



PCN 14\_0173

Alternate fab source for RS-232 & RS-485 Transceiver products.  
To enable additional wafer fabrication capacity



**Proposed Flow:**

